

Product Change Notification - SYST-21EDWO528

Date:

24 Feb 2020

Product Category:

32-bit Microcontrollers

Affected CPNs:



Notification subject:

ERRATA - PIC32MX1XX/2XX/5XX 64/100-pin Family Silicon Errata and Data Sheet Clarification

Notification text:

SYST-21EDWO528

Microchip has released a new Product Documents for the PIC32MX1XX/2XX/5XX 64/100-pin Family Silicon Errata and Data Sheet Clarification of devices. If you are using one of these devices please read the document located at PIC32MX1XX/2XX/5XX 64/100-pin Family Silicon Errata and Data Sheet Clarification.

Notification Status: Final

Description of Change: 1) Added silicon issues 17. Module: I/O Port - Initial Pin State and 18.

Module: USB Low-Speed Mode. **Impacts to Data Sheet:** None

Reason for Change: To Improve Productivity

Change Implementation Status: Complete

Date Document Changes Effective: 24 Feb 2020

NOTE: Please be advised that this is a change to the document only the product has not been changed.

Markings to Distinguish Revised from Unrevised Devices: N/A Attachment(s):

PIC32MX1XX/2XX/5XX 64/100-pin Family Silicon Errata and Data Sheet Clarification

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PIC32MX1XX/2XX/5XX 64/100-PIN FAMILY

PIC32MX1XX/2XX/5XX 64/100-pin Family Silicon Errata and Data Sheet Clarification

The PIC32MX1XX/2XX/5XX 64/100-pin family devices that you have received conform functionally to the current Device Data Sheet (DS60001290F), except for the anomalies described in this document.

The errata described in this document will be addressed in future revisions of the PIC32MX1XX/2XX/5XX 64/100-pin family silicon.

Note: The silicon issues discussed in the following pages are for silicon revisions with the Device and Revision IDs listed in Table 1 and Table 2. The last column of each table represents the latest silicon revision for the devices listed. If applicable, the silicon issues are summarized in Table 3.

Data Sheet clarifications and corrections, if applicable, start on page 10.

The silicon revision level can be identified using the current version of MPLAB® X IDE and Microchip's programmers, debuggers and emulation tools, which are available at the Microchip corporate web site (www.microchip.com).

For example, to identify the silicon revision level using MPLAB X IDE in conjunction with a hardware debugger:

- Using the appropriate interface, connect the device to the hardware debugger.
- 2. Open an MPLAB X IDE project.
- Configure the MPLAB X IDE project for the appropriate device and hardware debugger.
- 4. Select <u>Window > Dashboard</u>, and then click the **Refresh Debug Tool Status** icon ().
- The part number and the Device and Revision ID values appear in the **Output** window.

Note: If you are unable to extract the silicon revision level, please contact your local Microchip sales office for assistance.

The Device and Revision ID values for the various PIC32MX1XX/2XX/5XX 64/100-pin family silicon revisions are shown in Table 1 and Table 2.

TABLE 1: SILICON DEVREV VALUES FOR DEVICES WITH 256 KB OR 512 KB OF FLASH MEMORY

Part Number	Device ID ⁽¹⁾	Revision ID for Silicon Revision ⁽¹⁾
Part Number	Device ID(**)	Α0
PIC32MX150F256H	0x06A10053	
PIC32MX150F256L	0x06A11053	
PIC32MX170F512H	0x06A30053	
PIC32MX170F512L	0x06A31053	
PIC32MX250F256H	0x06A12053	
PIC32MX250F256L	0x06A13053	0.40
PIC32MX270F512H	0x06A32053	0x0
PIC32MX270F512L	0x06A33053	
PIC32MX550F256H	0x06A14053	
PIC32MX550F256L	0x06A15053	
PIC32MX570F512H	0x06A34053	
PIC32MX570F512L	0x06A35053	

Note 1: Refer to the "Memory Organization" and "Special Features" chapters in the current Device Data Sheet (DS60001290F) for detailed information on Device and Revision IDs for your specific device.

TABLE 2: SILICON DEVREV VALUES FOR DEVICES WITH 64 KB OR 128 KB OF FLASH MEMORY

Part Number	Device ID ⁽¹⁾	Revision ID for S	Revision ID for Silicon Revision ⁽¹⁾		
Part Number	Device iD(*)	Α0	A2		
PIC32MX120F064H	0x06A50053				
PIC32MX130F128H	0x06A00053				
PIC32MX130F128L	0x06A01053				
PIC32MX230F128H	0x06A02053	0x0	0x2		
PIC32MX230F128L	0x06A03053				
PIC32MX530F128H	0x06A04053				
PIC32MX530F128L	0x06A05053				

Note 1: Refer to the "Memory Organization" and "Special Features" chapters in the current Device Data Sheet (DS60001290F) for detailed information on Device and Revision IDs for your specific device.

TABLE 3: SILICON ISSUE SUMMARY

Module	Feature	Feature Item	Issue Summary	Device Flash Memory		Affected Revisions	
					Α0	A2	
ADC Reference: ADC006-14	Differential Nonlinearity	1.	The ADC module is not within the published data sheet specification when operating at a conversion rate above		Х	Х	
ADC000-14	Nonlineanty		500 ksps.	256/512	Х	_	
Clock	Clock Out	2.	A clock signal is present on the CLKO pin, regardless of the clock source and setting of the CLKO Enable Configuration bit, during a Power-on Reset (POR)	64/128 256/512	X		
			condition.	64/128	Х	Х	
JTAG	Boundary Scan	3.	Boundary scan in not supported.			^	
				256/512	X		
Watchdog Timer	Windowed Watchdog	4.	Clearing the Watchdog Timer inside the window when in Window mode may cause a reset.	64/128	Х	Х	
	viatoriaog		Third will be may easily a reset.	256/512	Х	_	
USB	Idle Interrupt	5.	USB Idle interrupts cease if the IDLEIF flag is cleared and the bus is left idle for more than 3 ms.	64/128	Х	Х	
	•		and the bus is left fale for more than 5 ms.	256/512	Х	_	
UART	Receive	6.	A receive FIFO overflow condition causes the shift register to stop receiving data and lose synchronization with the serial data stream.		Х	Х	
	Overflow				Х	-	
Comparator Voltage	_	7.	Some operational mode combinations of the Comparator Voltage Reference do not meet the data sheet specifications.		Х	Х	
Reference		, ,			Х	1	
Comparator Voltage		8.	The Comparator Voltage Reference always behaves as if		Х	Х	
Reference		0.	the CVRR bit is = 1, which specifies a range of 0 to 0.67 CVRSRC with a CVRSRC/24 step size.	256/512	Х	_	
OTMU	T.:		The EDGEN bit generates a glitch on the CTED input	64/128	Х	Х	
CTMU	Trigger	9.	causing a false trigger.	256/512	Х	_	
	Module			64/128	Х		
CTMU	Operation	10.	The CTMU module is not functional.	256/512	Х	_	
				64/128	Х	Х	
ADC	IV REF	11.	The IVREF input to the ADC is not functional.	256/512	Х	_	
			On power-up, the High-Voltage Detect Reset event flag,	64/128	Х	Х	
HVD	HVDR	12.	HVDR bit in the RCON register, is being set.	256/512	Х	_	
Dower Covins			On ovit from Sloop mode, the SLEER and IDLE status	64/128	Х	Х	
Power-Saving Modes	ldle	13.	On exit from Sleep mode, the SLEEP and IDLE status bits in the RCON register are being set.		Х	_	
					Х	Х	
UART	Auto-baud	14.	Auto-baud does not function to set the baud rate.	64/128 256/512	X		
			The Fleek Mercen Circle (CANYDENCE)	64/128			
I BUS Matrix I Flash Size I 15 I		15.	The Flash Memory Size register (BMXPFMSZ) was not programmed with the correct value.	256/512	Date code pre- 1750		
			cont in this revision of silicon.	230/312			

Legend: An 'X' indicates the issue is present in this revision of silicon;

shaded cells with an Em dash ('—') indicate that this silicon revision does not exist for this issue; blank cells indicate an issue has been corrected or does not exist in this revision of silicon.

TABLE 3: SILICON ISSUE SUMMARY (CONTINUED)

Module Feature		Item	Issue Summary	Device Flash	Affected Revisions	
	,		Memory (KB)	Α0	A2	
I/O Port	Drive	16.	Pins RD15 & RF13 should be considered 4x Sink		Х	Х
I/O Poit	Strength	10.	Driver Pins and not 8x Sink Driver Pins.	256/512	Х	_
I/O Port - Initial	Initial Pin	17.	Random pin active output on power up.	64/128	Х	Х
Pin State State		17.	Random pin active output on power up.	256/512	Х	Х
USB Low-	USB Low	10	LICE I are Cread made in maticular		Х	Х
Speed Mode Spee	Speed	Speed 18.	USB Low-Speed mode is not functional.	256/512	Х	Х

Legend: An 'X' indicates the issue is present in this revision of silicon;

shaded cells with an Em dash ('—') indicate that this silicon revision does not exist for this issue; blank cells indicate an issue has been corrected or does not exist in this revision of silicon.

Silicon Errata Issues

- **Note 1:** This document summarizes all silicon errata issues from all revisions of silicon, previous as well as current. The table provided in each issue indicates which issues exist for a particular revision of silicon based on Flash memory size.
 - **2:** The following applies to the Affected Silicon Revision tables in each silicon issue:
 - · An 'X' indicates the issue is present in this revision of silicon
 - Shaded cells with an Em dash ('—') indicate that this silicon revision does not exist for this issue
 - · Blank cells indicate an issue has been corrected or does not exist in this revision of silicon.

1. Module: ADC Reference: ADC006-14

When the ADC is configured for 10-bit operation, the specifications in the data sheet are not met for operation above 500 ksps.

Work around

For 600 ksps operation, RIN = 500 ohms, TSAMP = 2 TAD. The module specifications are shown in Table 4. For 1000 ksps operation, RIN = 200 ohms, TSAMP = 2 TAD. The module specifications are shown in Table 5.

TABLE 4: 600 KSPS OPERATION

Parameter No.	Symbol	Minimum	Typical	Maximum	Units		
AD17	RIN	_	_	200	Ohm		
ADC Accuracy – Measurements taken with External VREF+/VREF-							
AD21c	INL	-1.5	_	1.5	LSB		
AD22c	DNL	-1.4	_	2.1	LSB		
AD23c	GERR	-1.2		1.2	LSB		
ADC Accuracy – Measurements taken with Internal VREF+/VREF-							
AD21d	INL	-1.5	_	1.5	LSB		
AD22d	DNL	-1.4	_	2.1	LSB		

TABLE 5: 1000 KSPS OPERATION

Parameter No.	Symbol	Minimum	Typical	Maximum	Units		
AD17	RIN	_		200	Ohm		
ADC Accuracy – Measurements taken with External VREF+/VREF-							
AD21c	INL	-5.2	_	6.5	LSB		
AD22c	DNL	-3.4	_	7	LSB		
AD23c	GERR	-1.5		1.5	LSB		
ADC Accuracy – Measurements taken with Internal VREF+/VREF-							
AD21d	INL	-5.2		6.5	LSB		
AD22d	DNL	-3.4	_	7	LSB		

Device Flash	Device Silicon Revision				
Memory (KB)	A0	A2			
64/128	Χ	Х			
256/512	Х	_			

2. Module: Clock

A clock signal is present on the CLKO pin, regardless of the clock source and setting of the CLKO Enable Configuration bit, OSCIOFNC (DEVCFG1<10>), during a Power-on Reset (POR) condition.

Work around

Do not connect the CLKO pin to a device that would be adversely affected by rapid pin toggling or a frequency other than that defined by the oscillator configuration. Do not use the CLKO pin as an input if the device connected to the CLKO pin would be adversely affected by the pin driving a signal out.

Affected Silicon Revisions

Device Flash	I	Device Silicon Re			า
Memory (KB)	A0	A2			
64/128	Х	Χ			
256/512	Х	_			

3. Module: JTAG

Boundary Scan is not supported.

Work around

None.

Affected Silicon Revisions

Device Flash	Device Silicon Revision				
Memory (KB)	A0	A2			
64/128	Χ	Χ			
256/512	Χ	_			

4. Module: Watchdog Timer

When the Watchdog Timer module is used in Windowed mode, the module may issue a reset even if the user tries to clear the module within the allowed window.

Work around

None.

Affected Silicon Revisions

Device Flash	I	Device S	Silicon F	Revisior	1
Memory (KB)	A0	A2			
64/128	Χ	Χ			
256/512	Х	_			

5. Module: USB

If the bus has been idle for more than 3 ms, the IDLEIF interrupt flag is set. If software clears the interrupt flag and the bus remains idle, the IDLEIF interrupt flag will not be set again.

Work around

Software can leave the IDLEIF bit set until it has received some indication of bus resumption (i.e., Resume, Reset, SOF, or Error).

rı a sı m p A sı e	resume and Reset are the only interpose that should be following IDLEIF sertion. If the IDLEIF bit is set, it hould be okay to suspend the USB module (as long as this code is rotected by the GUARD and/or CTPEND logic). This will require oftware to clear the IDLEIF interrupt nable bit to exit the USB ISR (if sing interrupt driven code).
---	---

Device Flash	Device Silicon Revision				า
Memory (KB)	A0	A2			
64/128	Х	Х			
256/512	Χ	_			

6. Module: UART

During receive FIFO overflow conditions, the shift register stops receiving data, which causes the UART to lose synchronization with the serial data stream.

The only way to recover from this condition is to turn the UART OFF and ON until it synchronizes. This could require several OFF/ON sequences.

Work arounds

Work around 1:

Avoid the RX overrun condition by ensuring that the UARTx module has a high enough interrupt priority such that other peripheral interrupt processing latencies do not exceed the time to overrun the UART RX buffer based on the application baud rate. Alternately or in addition to, set the URXISEL bits in the UxSTA register to generate an earlier RX interrupt based on RX FIFO fill status to buy more time for interrupt latency processing requirements.

Work around 2:

If avoiding RX FIFO overruns is not possible, implement a ACK/NAK software handshake protocol to repeat lost packet transfers after restoring UART synchronization.

Affected Silicon Revisions

Device Flash	Device Silicon Revision				
Memory (KB)	A0	A2			
64/128	Χ	Χ			
256/512	Χ	_			

7. Module: Comparator Voltage Reference

Three of the four Comparator Voltage Reference operational modes, defined in Table 6, do not meet data sheet specifications.

TABLE 6:

CVRCON <cvrss></cvrss>	CVRCON <cvrr></cvrr>	Accuracy Specification	Actual Accuracy
0 = (AVDD/AVSS)	0 = (CVRSRC/32)	0.5 LSB	8.2 LSB
0 = (AVDD/AVSS)	1 = (CVRSRC/24)	0.25 LSB	0.34 LSB
1 = (VREF+/VREF-)	0 = (CVRSRC/32)	0.5 LSB	8.2 LSB

Work around

If possible, set both the CVRSS bit (CVRCON<4>) and the CVRR bit (CVRCON<5>) to '1', which specifies the Comparator Voltage Reference source CVRSRC = [(VREF+) - (VREF-)] and 0 to 0.67 CVRSRC with a step size of CVRSRC/24, respectively.

Affected Silicon Revisions

Device Flash	Device Silicon Revision				
Memory (KB)	A0	A2			
64/128	Х	Х			
256/512	Χ	_			

8. Module: Comparator Voltage Reference

The Comparator Voltage Reference always behaves as if the CVRR bit (CVRCON<5>) is equal to '1', which specifies a range of 0 to 0.67 CVRSRC with a step size of CVRSRC/24, instead of a range of 0.25 to 0.75 CVRSRC and a step size of CVRSRC/32.

Work around

If possible, set the CVRR bit (CVRCON<5>) = 1 (i.e., 0 to 0.67 CVRSRC, with CVRSRC/24 step size, respectively).

Device Flash	Device Silicon Revision				
Memory (KB)	A0	A2			
64/128	Х	Х			
256/512	Χ	_			

9. Module: CTMU

The EDGEN bit generates a glitch on CTED input causing a false trigger.

Work around

None.

Affected Silicon Revisions

Device Flash	Device Silicon Revision				
Memory (KB)	A0	A2			
64/128	Χ	Χ			
256/512	Χ	_			

10. Module: CTMU

The CTMU module is not functional.

Work around

None.

Affected Silicon Revisions

Device Flash	Device Silicon Revision				
Memory (KB)	A0	A2			
64/128	Χ				
256/512	Х				

11. Module: ADC

Converting the Internal Band Gap (IVREF) voltage source generates a High-Voltage Detect (HVD) event and aborts the conversion; therefore, this feature is not functional.

Work around

None.

Affected Silicon Revisions

Device Flash	I	Device S	Silicon I	Revision	1
Memory (KB)	A0	A2			
64/128	Х	Х			
256/512	Χ	_			

12. Module: HVD

On power-up, the High-Voltage Detect Reset, event flag (HVDR bit in the RCON register) is set incorrectly.

On a power-up, only the POR, BOR, and EXTR bits should be set with the proper VCAP bypass capacitor value, as stated in the current data sheet.

Work around

Check the status of the POR bit in the RCON register when checking the HVDR bit. If the POR bit is set, both bits can be cleared as the HVDR bit is a false detection. If the POR bit is clear, the HVDR bit has been correctly detected and can be handled according to the requirements of the application.

Affected Silicon Revisions

Device Flash	1	Device S	Silicon I	Revision	1
Memory (KB)	A0	A2			
64/128	Х	Χ			
256/512	Х				

13. Module: Power-Saving Modes

On exit from Sleep mode, both the SLEEP and IDLE status bits in the RCON register are set.

Work around

Add the following code to the user application at the point it wakes from Sleep mode:

```
rcon_var1 = RCON;
// ... enter Sleep mode
if (rcon_var1 & 0x4) Nop();
// If IDLE bit already set previously
// before sleep do nothing
else RCONbits.IDLE = 0x0;
// If IDLE bit is not set previously
// and is after Sleep mode then clear
```

Device Flash	Device Silicon Revision				
Memory (KB)	A0	A2			
64/128	Χ	Х			
256/512	Х	_			

14. Module: UART

The UART auto-baud feature is intended to set the baud rate during run time based on external data input. However, this feature does not function.

Work around

None.

Affected Silicon Revisions

Device Flash	Device Silicon Revision				
Memory (KB)	A0	A2			
64/128	Х	Х			
256/512	Х	_			

15. Module: Bus Matrix

The Flash Memory Size register (BMXPFMSZ) was not programmed with the correct value.

Work around

Use a fixed number based on the size of the part being used.

Affected Silicon Revisions

Device Flash		Device S	Silicon I	Revision	1
Memory (KB)	A0	A2			
64/128	Date	Date code			
256/512	pre-1750				

16. Module: I/O Port

RD15 & RF13 should be considered 4x Sink Driver Pins and not 8x Sink Driver Pins. See Parameter DO10, DO20, and DO20A in the data sheet.

Work around

None.

Affected Silicon Revisions

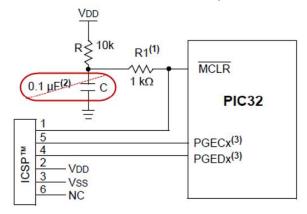
Device Flash	Device Silicon Revision				
Memory (KB)	A0	A2			
64/128	Χ	Χ			
256/512	Х	_			

17. Module: I/O Port - Initial Pin State

On power-up depending on the VDD ramp rate, the I/O pins can be in an active random output driving state if MCLR is active until a BOR event.

Work around 1:

If, not using an external reset supervisor IC or equivalent, remove the MCLR capacitor as shown below, and retain the MCLR Pull-up resistor.



Work around 2:

If using an external reset supervisor IC or equivalent, increase the value of the VCAP capacitor to \geq 47 μ f ceramic or solid tantalum capacitor with an ESR \leq 1 ohm.

Affected Silicon Revisions

Device Flash Memory (KB)	Device Silicon Revision					
	A0	A2				
64/128	Χ	Х				
256/512	Х	Х				

18. Module: USB Low-Speed Mode

USB Low-Speed mode in either Host or Device mode is not functional.

Work around 1:

Use USB Full-Speed mode.

Device Flash Memory (KB)	Device Silicon Revision					
	A0	A2				
64/128	Χ	Х				
256/512	Χ	Х				

Data Sheet Clarifications

The following typographic corrections and clarifications are to be noted for the latest version of the device data sheet (DS60001290F):

Note:

Corrections are shown in **bold**. Where possible, the original bold text formatting has been removed for clarity.

Features List

The Qualification and Class B Support features were incorrectly specified in the current version of the data sheet. The corrected information is as follows:

Qualification and Class B Support

• Class B Safety Library, IEC 60730

APPENDIX A: REVISION HISTORY

Rev A Document (10/2014)

Initial release of this document, issued for revision A0 silicon, which includes silicon issues 1 (ADC Reference: ADC006-14), 2 (Clock), 3 (JTAG), 4 (Watchdog Timer), 5 (USB), 6 (UART), 7 (Comparator Voltage Reference), 8 (Comparator Voltage Reference), 9 (CTMU), 10 (CTMU) and 11 (ADC).

Rev B Document (7/2015)

Updated silicon issues 6 (UART) and 11 (ADC).

Added silicon issues 12 (HVD) and 13 (Power-Saving Modes).

Rev C Document (4/2016)

Revised document for silicon revisions A2.

Added silicon issue 14 (UART).

Modified Silicon DEVREV Value Table 1 and added Silicon DEVREV Value Table 2.

Updated the Silicon Issue Summary table (Table 3) and silicon issue 9 (CTMU).

Updated all Affected Silicon Revision tables.

Rev D Document (6/2018)

Added silicon issue 15 (Bus Matrix).

Rev E Document (8/2018)

Added Silicon Issue 16 (16. Module:I/O Port).

Revision F Document (08/2019)

Added Data Sheet Clarification Features List.

Revision G Document (02/2020)

Added silicon issues 17. Module:I/O Port - Initial Pin State and 18. Module:USB Low-Speed Mode.

PIC32WX1XX/2XX/5XX 64/100-PIN							

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